

### Part Information

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## 01 Part Information

### (1) Design Record of The Target Part

### Overview of The Company / Factory Responsible for The Process

(a) Wafer Process: Company Z, Factory B

Mass production of the Z series of Parts has been started since the yyyy/mm month.  
Mass production is about xxM units.

Company name	Company Z, Factory W
Location	(City) / (Country)
Foundation	YYYY
Business Outline	Wafer Fabrication
Quality System Certification	ISO9002 (in yyyy) ISO14001 (in yyyy) IATF 16949 (in yyyy)

**02 MULTI-RESOURCE DIFFERENTIAL AND DETAILS OF ASSESSMENT**  
- Multi-resource Differential Assessment Sheet -

### 1. Manufacturing differential check with multi-resource application

[illegible]

## 01 Part Information

### (1) Design Record of The Target Part

### The Target Part

Part name	Part information	Supplement
Part Name or Series (Process) Name	xxx	
Operating Temperature Range	Ta= -40~125°C	
Maximum Operating Frequency	xxxMHz	
Process / Design rule	CMOS/ xxx nm	
PKG type (QFP, BGA, etc.)	QFP	
Number of pins	100	
Wafer Factory	Factory A / Factory B	Subject of the multi-resource
Assembly factory	Factory C	
Temperature Grade	AEC-Q100 Grade 1	
MSL	MSL3	

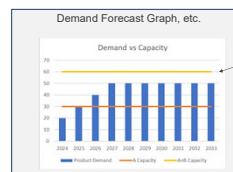
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## 01 PART INFORMATION

## 2. Multi-resource background [Reason, Purpose]

- Due to an increase in demand, the production capacity at Factory A is expected to be exceeded.

We are applying for a multi-resource application for an additional production base for the purpose of ensuring a stable supply of products.



The expected supply achievement after the application of multi-resource should also be described.

**02 MULTI-RESOURCE DIFFERENTIAL AND DETAILS OF ASSESSMENT**  
- Multi-resource Differential Assessment Sheet -

### 2a. Differential design checks for multi-resource applications

[illegible]

## 01 Part Information

### (1) Design Record of The Target Part

### Overview of The Company / Factory Responsible for The Process

(a) Wafer Process: Company Z, Factory A

Mass production of the xxx series of Parts has been started since the yyyy/mm month.  
Mass production is about xxM units.

Company name	Company Z, Factory W
Location	(City) / (Country)
Foundation	YYYY
Business Outline	Wafer Fabrication
Quality System Certification	ISO9002 (in YYYY) ISO 14001 (in YYYY) IATF 16949 (in YYYY)

## 02

## MULTI-RESOURCE DIFFERENTIAL AND DETAILS OF ASSESSMENT

**02 MULTI-RESOURCE DIFFERENTIAL AND DETAILS OF ASSESSMENT**  
- Multi-resource Differential Assessment Sheet -

## 2b. Verification of combination risk and definition of evaluation items

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